

External_Type	Material_Group	Substances	CAS_Number	Mass	Mass_Percentage_in_Leaf	Massmg
Die	Doped silicon	Silicon (Si)	7440-21-3	0.26	100.0	12.7
Subtotal				0.26	100	12.7
Wire	Pure metal	Aluminium (Al)	7429-90-5	0.26	100.0	12.75
	Pure metal	Aluminium (Al)	7429-90-5	0	100.0	0.19
Subtotal				0.26	200	12.94
Solder Paste	Lead alloy	Tin (Sn)	7440-31-5	0.01	5.0	0.45
	Lead alloy	Lead (Pb)	7439-92-1	0.16	85.0	7.65
	Lead alloy	Antimony (Sb)	7440-36-0	0.02	10.0	0.9
	Pure metal	Tin (Sn)	7440-31-5	0.06	5.0	2.95
	Pure metal	Silver (Ag)	7440-22-4	0.03	2.5	1.48
	Pure metal	Lead (Pb)	7439-92-1	1.12	92.5	54.58
Subtotal				1.4	200	68.01
Isolator	Aluminium alloy	Aluminium Trioxide (Al2O3)	1344-28-1	3.85	100.0	188
Subtotal				3.85	100	188
Lead Frame	Copper alloy	Phosphorous (P)	7723-14-0	0.01	0.03	0.25
	Copper alloy	Iron (Fe)	7439-89-6	0.02	0.11	0.92
	Copper alloy	Copper (Cu)	7440-50-8	17.16	99.84	838.66
	Copper alloy	Silver (Ag)	7440-22-4	0	0.02	0.17
	Copper alloy	Phosphorous (P)	7723-14-0	0.02	0.03	0.8
	Copper alloy	Iron (Fe)	7439-89-6	0.06	0.11	2.95
	Copper alloy	Copper (Cu)	7440-50-8	54.73	99.86	2674.25
Subtotal				72	200	3518
Post-plating	Pure metal	Tin (Sn)	7440-31-5	0.06	100.0	3
Subtotal				0.06	100	3
Mould Compound	polymer	Tetrabromobisphenol A/Epichlorohydrin polymer	40039-93-8	0.35	1.6	17.34
	Polymer	Phenol Formaldehyde resin (generic)	9003-35-4	1.44	6.5	70.46
	Polymer	Epichlorohydrin/Diethyleneglycol Epoxy resin (generic)	25928-94-3	2.88	13.0	140.92
	Filler	Silica fused	60676-86-0	17.3	78.0	845.52
	Carbon Black	Carbon black	1333-86-4	0.16	0.7	7.59
	Flame retardant	Antimony Trioxide (Sb2O3) - cas no. 1309-64-4	1309-64-4	0.04	0.2	2.17
Subtotal				22.17	100	1084
Total				100	100	4886.65

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